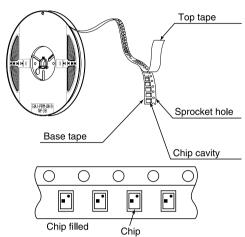
1)Minimum Quantity

Туре	Standard Quantity (pcs) Embossed Tape	
AF216M, AF816M, AH104F, AH104N	2000	
AH316M	3000	
AH083F, AH086M	1000	
AH212M	4000	

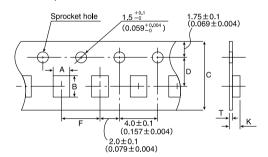
②Tape Material

Embossed Tape

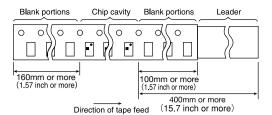


3Taping Dimensions

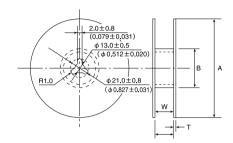
Embossed Tape



4 Leader and Blank Portion



5Reel size



Туре	Α	В	W	Т
AF216M, AH212M	178±2.0	50 min.	10.0±1.5	3.0 max.
AH316M	(7.0±0.08)	(2.0 min.)	(0.394±0.06)	(0.12 max.)
AF816M	178±2.0	50 min.	17.0±1.0	2.5 max.
AH083F	(7.0±0.08)	(2.0 min.)	(0.67±0.04)	(0.1 max.)
AH104F	330±2.0	100±1.0	25.5±1.0	3.0 max.
AH104N	(13.0±0.08)	(3.94±0.04)	(1.0±0.04)	(0.12 max.)
AH086M	330 ± 2.0	100 ± 1.0	17.0 ± 1.0	2.5 max.
	(13.0±0.08)	(3.94±0.04)	(0.67±0.04)	(0.1 max.)

Unit : mm (inch)

®Top Tape Strength

The top tape requires a peel-off force of $0.1 \sim 0.7 N$ in the direction of the arrow as illustrated below.



Type	Chip Cavity		Tape Widthness		Insertion Pitch	Tape Thickness MAX.	
Type	A	В	С	D	F	K	T
AF216M	1.85±0.2	2.75±0.2	8±0.2	3.5±0.1	4±0.1	1.95	0.3
	(0.073±0.008)	(0.108±0.008)	(0.315±0.008)	(0.138±0.004)	(0.157±0.004)	(0.077)	(0.012)
AF816M	1.95±0.2	8.4±0.2	16±0.3	7.5±0.1	4±0.1	2.05	0.35
	(0.077±0.008)	(0.331±0.008)	(0.630±0.012)	(0.296±0.004)	(0.157±0.004)	(0.081)	(0.014)
AH316M	1.9±0.2	3.5±0.2	8±0.2	3.5±0.1	4±0.1	0.85	0.3
	(0.075±0.008)	(0.138±0.008)	(0.315±0.012)	(0.138±0.004)	(0.157±0.004)	(0.033)	(0.012)
AH083F	3.35±0.2	8.35±0.2	16±0.3	7.5±0.1	8±0.1	1.55	0.3
	(0.132±0.008)	(0.329±0.008)	(0.630±0.012)	(0.295±0.004)	(0.315±0.004)	(0.061)	(0.012)
AH104F,	4.35±0.2	10.35±0.2	24±0.3	11.5±0.1	8±0.1	1.55	0.3
AH104N	(0.171±0.008)	(0.407±0.008)	(0.945±0.012)	(0.435±0.004)	(0.315±0.004)	(0.061)	(0.012)
AH086M	6.25±0.2	8.26±0.2	16±0.3	7.5±0.1	12±0.1	1.3	0.3
	(0.246±0.008)	(0.325±0.008)	(0.630±0.012)	(0.296±0.004)	(0.473±0.004)	(0.051)	(0.012)
AH212M	1.5±0.2	2.3±0.2	8±0.3	3.5±0.1	4±0.1	1.5	0.3
	(0.059±0.008)	(0.091±0.008)	(0.315±0.012)	(0.138±0.004)	(0.157±0.004)	(0.059)	(0.012)

Unit: mm (inch)

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RELIABILITY DATA

10 " T	
Operating Temperature Range	25 1 2502
Specified Value	-20~+80°C
Storage Temperature Range	
Specified Value	-40∼+85°C
[Test Methods and Remarks] ※with being taped, −20∼+40°C	
3. Solderability	
Specified Value	At least 90% of immersed terminal surface is covered by new solder.
[Test Methods and Remarks] Solder temperature: 230±5°C Duration: 3±1 sec. Preconditioning: Preheating at 150°C after immersion	into flux.
4. Thermal Shock	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
[Test Methods and Remarks] 1 hour of recovery after 10 times of 30min.immersion alter	rnately at -40° C and 85°C of temperature,followed by evaluating electrical characteristics.
5. High Temperature Storage Test	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
[Test Methods and Remarks] 1 hour of recovery under standard condition after 96 hour	s recovery with 85°C of temperature, followed by evaluating electrical characteristics.
6. Low Temperature Storage Test	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
[Test Methods and Remarks] 1 hour of recovery under standard condition after 96 hour	s recovery with -40° C of temperature, followed by evaluating electrical characteristics.
7. Humidity Storage Test	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
[Test Methods and Remarks] 1 hour of recovery under standard condition after 96 hour	s recovery with 60°C of temperature, 90~95% relative humidity followed by evaluating electrical characteristics.
8. Resistance to Reflow	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
[Test Methods and Remarks] Two times of reflow soldering by recommended profile att	ached, followed by evaluating electrical characteristics.

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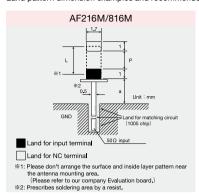
1. PCB Design

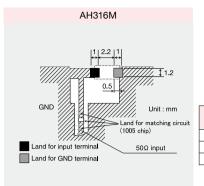
Precautions

◆Land pattern design
Please do not arrange the surface and inside layer pattern near the antenna mounting area.

◆Land pattern design

Land pattern dimension examples and recommended antenna land pattern

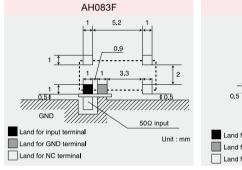


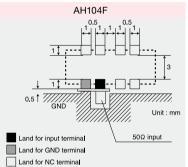


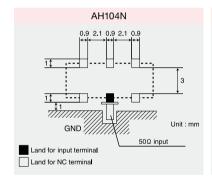
Туре	Dimensions		
	L	Р	а
AF216M	2.5	1.5	3
AF816M	8	7	5
AH212M	2	1	3

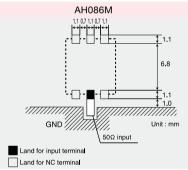
Unit: mm

Technical Considerations









2. Soldering

◆Conditions of Reflow soldering (for reference)



· Pb Free Reflow Profile Reflow Soldering 300 Peak 260°C max 200 100 Preheating 150°C Heating above 230°C 40sec max 60sec min Duration (seconds)

temperature pattern of reflow furnace temperature 250 200 150 20~30 about 60 55~75

Duration(seconds)

- Components should be preheated to within 100 to 130℃ from soldering temperature.
- * Assured to be reflow soldering for 2 times.

Note: The above profiles are the maximum allowable soldering condition, therefore these profiles are not always recommended.

3. Storage Conditions

Storage conditions

- The Products should not be used in the following environments:
 exposure to special gases such as (C12, NH3, SOx, NOx)

 - exposure to volatile gas or inflammable gas
 exposure to a lot of dust

Precautions

- exposure to water or condensation
- exposure to direct sanlight or freezing 2. The Products should be kept in the following conditions:
 - Temperature: −10~+40°C
 Humidity: 70%RH max.
- 3. The products should be used within 6 months after delivery. In case of storage over 6 months, solderability shall be checked before actual usage.
- Please contact our offices for further details of specifications.
 - All of the standard values listed here are subject to change without notice due to technical improvements.

Therefore, please check the specifications carefully before use.

· Reflow profile

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